Materials Declaration

Package	LFCSP
Body Size	4 X 4 X 1.45mm (1.75mm exposed pad)
LeadCount	16
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84.0	4.99 E-03	94557
Multiaromatic Resin	16.0	9.50 E-04	18011

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.50	2.26 E-02	428484
Fe	2.35	5.45 E-04	10328
Zn	0.12	2.78 E-05	527
P	0.03	6.96 E-06	132

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	5.30 E-04	10044

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	7.70 E-04	14592

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.9	6.00 E-04	11371

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	1.27 E-02	240676

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	77.0	6.93 E-03	131330
Resin	23.0	2.07 E-03	39228

Seal Glass

Lead	85.0	3.23 E-05	612
Zn borosilicate glass frit	15.0	5.70 E-06	108

Molding Compound

Item	PPM	Method
Pb	None Detected	US EPA 3052. ICP-OES
Cd	None Detected	US EPA 3052. ICP-OES
Hg	None Detected	US EPA 3052. ICP-OES
Cr+6	None Detected	EPA 3060A & 7196A. UV-VIS
PBB	None Detected	Analysis performed by GC/MS
PBDE	None Detected	Analysis performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	None Detected	US EPA 3052. ICP-OES
Cd	None Detected	US EPA 3052. ICP-OES
Hg	None Detected	US EPA 3052. ICP-OES
Cr+6	None Detected	EPA 3060A & 7196A. UV-VIS
PBB	None Detected	Analysis performed by GC/MS
PBDE	None Detected	Analysis performed by GC/MS

Package Totals

Weight (g)	PPM
5.28 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

9/11/06